

03-28-2005



102863507

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies)

Niandi Han
Hong Shih
Danny Lu

4/6/04
4/9/04
4/2/04

Li Xu
Yang Zhang
Jennifer Y. Sun

4/2/04
4/6/04
4/5/04

2. Name and address of receiving party(ies)

Name: Applied Materials, Inc.

Internal Address: Patent Department

Mail Stop 2061

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement ☐ Change of Name

☐ Other

Execution Date:

Street Address: P.O. Box 450A

City: Santa Clara State: CA ZIP: 95052

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s): 10/824,123

If this document is being filed together with a new application, the execution date of the application is: April 13, 2004

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Ashok Janah

Janah & Associates

Address: 650 Delancey Street, Ste#106
San Francisco, CA 94107

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)..... \$ 40.00

8. Please charge any additional fees or credit any

(Attach duplicate copy of this page if paying by deposit account)

10/14/2004

00000208

1

8021

\$40.00

04/13/2004

DA 501074

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Robert W. Mulcahy, Reg. No. 25,436

Name of Person Signing

Signature

Date

APRIL 13, 2004

Total number of pages including cover sheet, attachments, and document: 9

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Commissioner of Patents and Trademarks
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ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- | | |
|---|--|
| 1) Nianci Han
1236 Montcourse Lane
San Jose, CA 95131
U.S.A. | 2) Li Xu
1738 Fumia Drive
San Jose, CA 95131
U.S.A. |
| 3) Hong Shih
19048 E. Arquez Ave
Walnut, CA 91789
U.S.A. | 4) Yang Zhang
1066 Peralta Avenue
Albany, CA 94706
U.S.A. |
| 5) Danny Lu
542 Shelley Court
Milpitas, CA 95035
U.S.A. | 6) Jennifer Y. Sun
9964 Alpine Terrace
Sunnyvale, CA 94086
U.S.A. |

(hereinafter referred to as Assignors), have invented a certain invention entitled:

"PROCESS CHAMBER COMPONENT HAVING ELECTROPLATED YTTRIUM CONTAINING COATING"

☒ which is attached hereto

☐ for which application for Letters Patent in the United States was filed on _____, under Serial No. _____, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title, and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates, and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer, and convey to Assignee the full and exclusive right, title, and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International

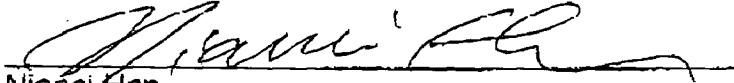
Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title, and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title, and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions, and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives, and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1)	<u>4/6/04</u> Date	<u></u> Nianci Han
2)	_____ Date	_____ Li Xu
3)	_____ Date	_____ Hong Shih
4)	_____ Date	_____ Yang Zhang
5)	_____ Date	_____ Danny Lu
6)	_____ Date	_____ Jennifer Y. Sun

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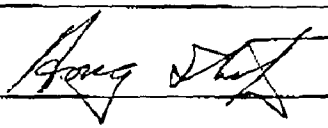
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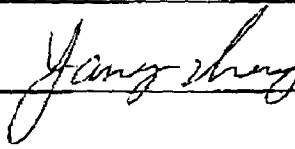
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